



236-Byte ISO14443A RFID/NFC Tag IC with built in ADC for Galvanostat sensor interface REV 1.5

Features Summary

Sensor Interface

- Galvanostat sensor interface circuit
 - Voltage is measured by applying current source
 - $_{\odot}\,$ Effective voltage range: 0.12 to 1.2V
 - Resistance sensing range: 250 Ω 400 k Ω
 - Capacitance sensing range: 25 pF to 7.5 μF
- Programmable current source
 - 2 ranges
 - 8 504 μA @ 8μA/Step ± 4 μA
 - 1 63μA @ 1μA/Step ± 0.5 μA
- Built-in ADC
 - 10-Bit accuracy
 - $_{\odot}\,$ Selectable post processing average
 - Adjustable conversion starting point to avoid uplink to ensure power stability.
 - Configurable built-in voltage buffer for highimpedance sensor
 - 1.28V temperature compensate voltage reference
 - Conversion rate from 8 ms to 205 ms
- Adjustable voltage limiter for preventing sensor burning or overvoltage
 - $\circ~$ 1.28 V
- Adjustable sensor biasing frequency for supporting wide capacitance-range sensor
 300 Hz - 50 kHz
- Adjustable sampling point for supporting various settling time
 - ο 10 1,808 μs
- Adjustable warm up clock for pre-biasing sensor
 8 491,528 clocks/ f,adc

Applications

- Chemical sensor NFC tag
- Light/ humidity sensing NFC tag

RF Interface

- Compliant with ISO14443A 106 kbps
- NFC Forum tag type 2

Memory

- 236 bytes addressable EEPROM
- 192 bytes user memory EEPROM
- EEPROM organization enabling NDEF format
- EEPROM zone for initializing register automatically reload after power up
- Up to 100,000 erase/write cycles
- Up to 10 years memory retention at 70°C

Operating Conditions

- Operating temperature: 0°C to 55°C
- Storage temperature: -40°C to 85°C

Package Information

- QFN 3x3 16 leads
- Au-bumped 12-inch die on wafer ring
- Pad size: 80 µm x 80 µm



Ordering Information

Part No.	Description	Package	Marking	Product Status
P40CDC60DU0UT4010R6	SIC4340-10, Galvanostat sensor interface with NFC type 2 DOWTB, UV sheet, Wafer ring, Dice	DOWTB	N.A.	Released
P40CVQK4P20UT4010C2	SIC4340-10, Galvanostat sensor interface with NFC type 2 QFN 0.85 mm, Canister, IC	QFN	4340C	Released

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Die and Package

Die Information



Figure 1: Die Information (Dimension in μ m)

Table 1: Pad description

Pad	Symbol	Туре	Description	
1	S0	Analog	Sensor connection pad 0	
2	S1	Analog	Sensor connection pad 1	
3	S2	Analog	Sensor connection pad 2	
4	RF1	Power	RF-Coil connection pad 1	
5	RF2	Power	RF-Coil connection pad 2	
6	HV	Power	Unregulated power supply to connect with external decoupling cap	
7	VDD	Power	ADC power supply to connect with external decoupling cap	
8	GND	Power	Ground (Power Ground and signal ground)	



Pin configuration



Figure 2: QFN 3x3 Pin arrangement (Top view)

Table 2: Pin description					
Pin No.	Symbol	Туре	Description		
2	S1	Analog	Sensor connection pin 1		
4	S2	Analog	Sensor connection pin 2		
6	RF1	Power	RF-Coil Connection pin 1		
8	RF2	Power	RF-Coil Connection pin 2		
10	HV	Power	Unregulated power supply to connect with external decoupling cap		
12	VDD	Power	ADC power supply to connect with external decoupling cap		
14	GND	Power	Ground (power ground and signal ground)		
16	S0	Analog	Sensor connection pin 0		